# Netra™ ft 1800 Hardware Reference Manual



THE NETWORK IS THE COMPUTER  $^{\text{\tiny{TM}}}$ 

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# **Preface**

This manual describes the hardware components of the Netra ft 1800 system.

# Who Should Use This Guide

This guide is intended to be read by installation engineers, hardware support personnel and service personnel. It is not intended for the end user of the system.

# How This Guide Is Organized

The guide is arranged as follows:

Chapter 1 "Introduction" provides an overview of the Netra ft 1800 system.

Chapter 2 "Motherboards" describes the architecture and functionality of the motherboards.

Chapter 3 "CPUsets" provides details of the CPUset components and the core of the system.

Chapter 4 "Mass Storage" shows how the drive chassis and hard disk drives work.

Chapter 5 "Removable Media Modules" describes the CD-ROM and optional DAT tape drives and the RMM chassis.

Chapter 6 "Console, Alarms and Fans" contains details and explanations of the functionality of the CAF module.

Chapter 7 "PCI Modules" gives details of the different PCI cards which can be used in the system.

Chapter 8 "Power Supply Units" describes the power supplies and how they are controlled.

Appendix A "RCP Status Information" lists the contents of the RCP status information.

The "Glossary" defines various terms and acronyms used in this manual.

# **Related Documentation**

- Netra ft 1800 Software Release Notes (Part No. 805-4527-10)
- Netra ft 1800 Hardware Release Notes (Part No. 806-0179-10)
- Netra ft 1800 User's Guide (Part No. 805-4529-10)
- Netra ft 1800 Reference Manual (Part No. 805-4532-10)
- Netra ft 1800 Developer's Guide (Part No. 805-4530-10)
- Netra ft 1800 CMS API Developer's Guide (Part No. 805-5870-10)
- Netra ft 1800 CMS Developer's Guide (Part No. 805-7899-10)
- Netra ft 1800 Installation Guide (Part No. 805-4533-10)
- Netra ft 1800 Compliance and Safety Manual (Part No. 805-7019-10)

# **Typographic Conventions**

 TABLE P-1
 Typographic conventions

Typeface or Symbol	Meaning	Examples
AaBbCc123	The names of commands, files, and directories; on-screen computer output.	Edit your .login file. Use ls -a to list all files. % You have mail.
AaBbCc123	What you type, when contrasted with on-screen computer output.	% <b>su</b> Password:
AaBbCc123	Book titles, new words or terms, words to be emphasized. Command-line variable; replace with a real name or value.	Read Chapter 6 in the <i>User's Guide</i> . These are called <i>class</i> options. You <i>must</i> be root to do this. To delete a file, type rm <i>filename</i> .

# **Symbols**

**Note** – A note provides information which should be considered by the reader.



**Caution** – Cautions identified by this Attention icon carry information about procedures or events which if not considered may cause damage to the data or hardware of your system.



**Caution –** Cautions identified by this Hazard icon carry information about procedures which must be followed to reduce the risk of electric shock and danger to personal health. Follow all instructions carefully.

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# Introduction

This chapter provides a general introduction to the concept and design of the Netra ft 1800 computer system.

The Netra ft 1800 is a rack-mounted server that can be configured to be a hardware fault tolerant or a high-availability system.

In its fault tolerant configuration, the Netra ft 1800 is designed to have no single point of failure (SPF). The fault tolerant configuration includes both replication of hardware to enable the system to continue in the event of a single hardware failure, and monitoring features to enable detection of the failure. All electrical components, including motherboards, can be replaced without shutting down the system.

**Note** – In this manual, a *fault tolerant* system configuration refers to one on which no single hardware failure can disrupt the system operation. A second hardware failure, if it occurs before the first failure is repaired, may stop the system.

# 1.1 System Features

The core of the system is the CPUset. Two CPUsets are used in the fault tolerant configuration, providing a twin-element virtual core in which both elements execute identical code. Each CPUset forms the basis of a *side*. A side consists of the CPUset and motherboard, and some or all of the following features associated with it:

- Console, alarms and fans
- Network connections (Ethernet and PCI)
- Disk chassis
- Removable media module
- Power supplies.

The CPUsets work in lockstep synchronization. Each processor on one CPUset exactly mirrors the work of the same processor on the other CPUset. CPUset failures are detected by hardware-comparison logic which is integral to the Netra ft 1800 motherboard. Because comparison of the CPUsets occurs only at I/O accesses, it does not cause the system to suffer significant performance loss. In a working Netra ft 1800, comparisons can take place millions of times per second. If a discrepancy occurs, the CPUsets verify which CPUset failed, configure the failed CPUset out of the core and continue normal processing on the remaining CPUset.

This design ensures that the processing element of the system is always available and can be completely trusted. The I/O functionality can then be implemented with redundant controllers using the processor core to detect and correct any I/O errors with intelligent software.

System components are housed in a rack-mountable chassis. See the Netra ft 1800 Installation Guide for details.

The system is designed to be mounted in 19, 23 and 24-inch, and 600-mm industry standard racks using adapter flanges to convert to the appropriate rack width.

### 1.2 **System Components**

The main system components (with their mnemonic abbreviations) are:

- Motherboard (MBD) (described in Chapter 2 "Motherboards").
- CPUset (CPU) (described in Chapter 3 "CPUsets").
- Disk drive (HDD) (described in Chapter 4 "Mass Storage").
- Disk chassis (DSK) (described in Chapter 4 "Mass Storage").
- Removable media chassis (RMM) (described in Chapter 5 "Removable Media Modules").
- Console, alarms and fans (CAF) (described in Chapter 6 "Console, Alarms and Fans").
- PCI carrier, containing an industry-standard PCI card (PCI) (described in Chapter 7 "PCI Modules").
- DC power supply unit (PSU) (described in Chapter 8 "Power Supply Units").

Each of these components is provided as a field replaceable unit (FRU) called a module. The characteristics of modules are described in Section 1.4 "Common Features of Modules" on page 1-4. Motherboards are replaceable from the back of the system. All other modules are replaceable from the front of the system, and are referred to as front-replaceable modules.

Modules in the system are configured in software to provide the subsystems that deliver the fault tolerant functionality of the system. The subsystems are:

Processor subsystem (providing processing and central control).

- Ethernet subsystem (providing fault tolerant network connections).
- Disk subsystem (providing mass storage).

Modules and subsystems are configured into and out of the system via the Configuration Management System software (CMS). A module is available to the system only once it has been configured in via the CMS. Each module belongs to one side only in a fault tolerant system

See the Netra ft 1800 User's Guide for full descriptions of the subsystems and the CMS.

In addition, the system has a chassis in which the other components are mounted.

#### 1.3 **hotPCI**

hotPCI is an implementation of the PCI bus designed to minimize the probability that a fault on a module will corrupt the bus, and so to ensure that the system control mechanism runs without interruption. hotPCI has the following features:

- Standard 32- or 64-bit PCI is available at the I/O slots.
- The bus enables hot replacement of modules: when a slot is empty, components on the motherboard isolate power and data, and the slot does not carry the bus signals.
- Extra I<sup>2</sup>C connection enables modules to carry serial number and history information on the I<sup>2</sup>C EEPROM.

Devices which perform system I/O are referred to as I/O devices. These include:

- PCI cards
- **■** Internal Ethernet interfaces
- SCSI drives.

I/O devices perform DMA to and from the CPUset main memory to move I/O data. CPUsets perform PIO access to I/O devices.

These devices cannot perform DMA to other I/O devices, only to main memory.

Each side of Netra ft 1800 has a separate IOMMU structure, which prevents I/O devices corrupting main memory other than that allocated to that I/O device.

### 1.4 Common Features of Modules

This section describes the features common to all modules in the system. Where a module is described in later parts of this manual, it is assumed to have the features described in this section unless stated otherwise.

### 1.4.1 Simple and Safe Hot Replacement

Modules can be replaced without shutting down the system. They are designed to be simple to replace, with minimal risk of damage. Modules have the following features to ensure this:

- It is not possible to damage a module electronically by accidentally plugging it into the wrong slot, or inserting it upside-down in the correct slot.
- The modules are physically robust, with sensitive parts shielded by covers. During maintenance, ESD-safe procedures must be used.
- All firmware within modules is downloadable when the module is configured into the system.
- All front-replaceable modules have an injection mechanism which provides a positive lock. See Section 1.4.4 "Module Injection Mechanisms" on page 1-6.
- All repair operations to front-replaceable modules and the motherboards can be carried out by one person. All modules can be replaced individually, without removing any other module. (Replacing the disk chassis DSK requires the prior removal of any HDD modules inserted in it.)
- The time required to physically replace a failed front-replaceable module is less than two minutes. This does not include re-integration time.

### 1.4.2 LED Indicators

All front-replaceable modules have a consistent front panel design with a 5 mm green *Power* LED which is lit when the module is powered on and a 5 mm red *Fault* indicator. When lit by the CMS, this LED indicates that a module is faulty and needs changing. When the module is removed, this LED is extinguished and will not remember that it was lit. Memory of past failures is dealt with by the service log (see Section 1.4.3 "Module Identity and Logs" on page 1-5).

The CAF module contains an additional green *Power* LED which is lit when the associated motherboard is powered on, and a red *Fault* LED which is lit when a fault is detected on the motherboard.

The CPUsets have additional 3 mm amber LEDs, which are described in Section 3.3 "CPUset LEDs" on page 3-7.

The states of the module LEDs are summarized in TABLE 1-1.

TABLE 1-1 **Module LED States** 

Fault (red)	Power (green)	Description
off	off	Module is not in use
off	on	Module is operating
on	off	Faulty module
on	on	Faulty module, still in use

Position as well as color is used in all indicators so that color-blind users can still perform replacements.

#### 1.4.3 Module Identity and Logs

All modules hold their identity in a machine-readable form and write key events to a service log in the I<sup>2</sup>C EEPROM. The log data includes power-on hours, last repair date, number of failures during its lifetime and reason for last failure. The system automatically updates the information in the log. It is possible for the system administrator to display this maintenance-related data, and the serial number and module type. An extract of status log is written to a module after it has failed.

# 1.4.4 Module Injection Mechanisms

All modules have one or two injection mechanisms. They are all similar in function and usage. Common features are an actuator enabling the module's electrical connection to the motherboard, and a lever which physically engages and disengages the module.

With the exception of the disk drives (HDDs), the actuator operates a microswitch which directly controls power rail switching to the module. The actuator also locks the mechanism when in the closed position, preventing casual operation. When the latch is disengaged a red dot is exposed to facilitate identification of disengaged injectors.

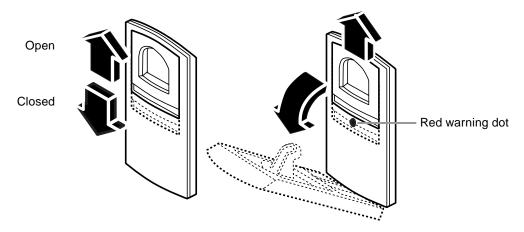


FIGURE 1-1 Typical Module Injector/Ejector Lever

The DSK and RMM modules have a sliding latch on an ejector handle. The latch controls the electrical connection to the motherboard. When it is closed (pushed to the right), the electrical connection is engaged; when it is open (pushed to the left), the electrical connection is disengaged. The handle is lifted to disengage the module physically, and lowered to engage it.

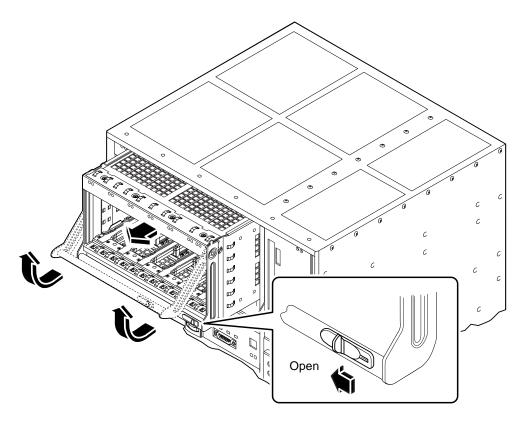


FIGURE 1-2 DSK and RMM Injector/Ejector Mechanism

#### The Maintenance Buses 1.4.5

There is a maintenance bus connection to every front-replaceable module except HDD modules. Maintenance bus control of the HDD modules is implemented within the DSK module. The maintenance buses allow the processor subsystem to monitor and control the operation of the whole Netra ft 1800 system.

Examples of the traffic carried on a maintenance bus are:

- The environmental signals from modules, which indicate their temperature.
- Signals that power sections of the modules on and off.
- Information written to the EEPROM service log.

The maintenance bus is also used to light the Fault LED on a module.

See Section 2.5 "Maintenance Buses" on page 2-5 for full information about the maintenance buses.

#### Locations for Modules 1.4.6

A location is a slot where a module can be inserted. Each location has a unique name and is clearly marked on the chassis.

TABLE 1-2 Module Locations

Module	Mnemonic	Side A Locations	Side B Locations
Motherboard	MBD	A-MBD	B-MBD
CPUset	CPU	A-CPU	B-CPU
Disk chassis	DSK	A-DSK	B-DSK
Disk drive	HDD	A-DSK0 A-DSK1 A-DSK2 A-DSK3 A-DSK4 A-DSK5	B-DSK0 B-DSK1 B-DSK2 B-DSK3 B-DSK4 B-DSK5
Removable media chassis	RMM	A-RMM	B-RMM

**TABLE 1-2** Module Locations (Continued)

Module	Mnemonic	Side A Locations	Side B Locations
Console, alarms and fans	CAF	A-CAF	B-CAF
Power supply	PSU	A-PSU0	B-PSU0
11 3		A-PSU1	B-PSU1
		A-PSU2	B-PSU2
PCI carrier	PCI	A-PCI0	B-PCI0
		A-PCI1	B-PCI1
		A-PCI2	B-PCI2
		A-PCI3	B-PCI3
		A-PCI4	B-PCI4
		A-PCI5	B-PCI5
		A-PCI6	B-PCI6
		A-PCI7	B-PCI7

# 1.5 Hot Insertion

The term Hot Insertion refers to the ability to replace modules without halting or power-cycling the system. All modules, including the motherboards, support this facility. During the replacement procedure, the module being replaced is disabled using the Configuration Management System (CMS).

Hot insertion is supported by three major features of the system:

- Power rail isolation
- Bus signal isolation
- Maintenance bus.

### 1.5.1 Power Rail Isolation

All front-replaceable modules, except the hard disk drives (HDDs) and RMM drives, interface directly with the motherboard. The PSU modules provide 14V supply rails which are distributed to the remaining modules through FET circuit breakers located on the motherboard. There are also 5V and 3.3V rails distributed to the CPUsets only and which are protected within the PSUs. The FET circuit breakers are enabled solely by the actuators in the injection mechanisms as described in Section 1.4.4 "Module Injection Mechanisms" on page 1-6.

All modules except CPUsets and motherboards operate from dedicated power rails derived from local regulators within their modules. These circuits are powered under software control and default to the 'off' state after the module has been inserted.

The HDD module injection mechanism has no effect on the power to the disk drive. Power to the HDDs is supplied from individual regulators inside the DSK module which default to the 'on' state on HDD insertion. When the CMS is used to disable the HDDs, bus activity to the drive is halted and the drive's local power regulator is disabled. To avoid the risk of data corruption or physical damage, HDD modules should not be removed until at least 30 seconds after being disabled.

#### 1.5.2 **Bus Signal Isolation**

Where a module interfaces with a shared bus, it is isolated from the bus during replacement. This isolation is achieved by using bus switches on the motherboards at the interface with each module. Only when the module's power supply is established will the module then enable the bus switches, preventing disturbances on the bus during replacement and removing the need to halt the bus.

Separate radial signals are passed through the bus switches during power cycling in order to protect them from hazardous currents.

The CPUset modules interface with both motherboards, and are isolated by a separate set of bus switches on each motherboard.

The DSK module complies fully with SCSI hot-plug requirements and supports HDD module replacement without the need for bus switches.

#### 1.5.3 Maintenance Bus

The maintenance bus provides the CMS with the ability to control the module power regulators.

#### 1.5.4 **PSU Modules**

The PSU modules on each side (that is, not across sides) current-share their output supply rails with (n+1) redundancy. This allows a PSU to be removed and replaced without prejudice to the system's power requirements. A power supply which has been inserted in the 'off' state can be enabled using the CAF ON switch. Because PSUs remember the state they were in the last time they were enabled, a PSU which was previously 'on' will power on as soon as it is inserted.

Power supplies can also be switched using RCP commands – refer to Section 2.6.2 "RCP Commands" on page 2-9.

### 1.5.5 Motherboards

Whilst both motherboards can be replaced individually without stopping the system, the replacement procedure is completely different from that for the other modules, and is very precisely defined. Refer to the *Netra ft 1800 User's Guide* for a full description of the procedure.

# **Motherboards**

The motherboard provides the communication between the modules that are connected to the slots on the motherboard. The main functional areas of the motherboard are:

- Bridge (two per motherboard)
- PCI I/O slots
- Interrupts
- Clock generation
- Maintenance bus
- Module power isolation
- Two UltraSCSI controllers for the disk chassis and removable media module
- Two PCI Ethernet controllers.

Each side of the system has its own motherboard. Motherboards are independently hot-replaceable from the rear of the system. When it is installed, each motherboard has a metal cover which provides mechanical protection and an EMI screen.

The standard LEDs on the CAF module indicate the state of the motherboard on the same side. A second set of *Power* and *Fault* LEDs on each motherboard is visible from the rear of the chassis (see FIGURE 2-3 on page 2-15 and FIGURE 2-4 on page 2-16). The other motherboard LEDs and indicators are described in Section 2.10 "LEDs and Indicators" on page 2-14.

The overall dimensions of the motherboards are 429 mm (w) x 821 mm (h) x 95 mm (d) (16.9 inches x 32.3 inches x 3.75 inches).

# 2.1 Bridge

The bridge forms an interface between the CPUsets and the I/O devices. Each motherboard has two bridges, each of which operates in one of two modes:

- Combined mode the bridge routes PCI addresses and data from the synchronized CPUsets to and from the device bus. It compares the I/O cycles generated by the CPUsets to ensure they are operating correctly; if there is a discrepancy, the bridge goes into an error limitation mode (EState) during which device I/O is prevented and diagnostic information is collected.
- Split mode the bridge arbitrates PCI address and data from the CPUsets on to the device bus. No I/O comparisons are made.

The mode in which the bridge operates is controlled by the software split utility. See the Netra ft 1800 User's Guide for information.

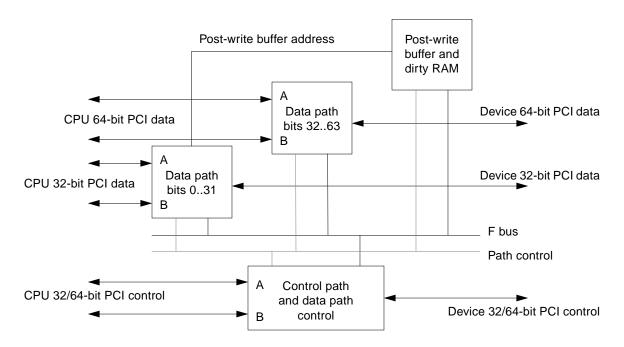


FIGURE 2-1 Overall Bridge Architecture

The bridge consists of three devices which in combination provide the following features:

- In either mode:
  - Two CPUset PCI bus interfaces
  - One PCI bus for I/O devices
  - PCI bus transaction routing
  - PCI bus error detection
  - Post write buffer access for error diagnosis
  - Arbitration for up to six devices on the PCI bus.
- In combined mode:
  - EState detection for CPUset PCI bus transactions
  - Post write buffer interface for CPUset transaction in EState.
- In split mode:
  - CPUset/CPUset transaction routing
  - Arbitration between CPUset PCI buses
  - Dirty RAM for DMA write monitoring.

The bridge provides the following functions:

- Comparing in sync accesses to PCI devices. A mismatch causes an error state which is signaled to all processors in the system by means of an interrupt.
- Control signal comparison, to ensure that control signals on each CPUset are asserted and negated on the same clock.
- Access validation, including the collection of diagnostic information for hardware failures.
- Decoding the geographical addresses of PCI devices.
- Access control via the slot response register.
- Supporting differing data registers, to allow the examination of data that may be different on each CPUset. See Section 2.8 "Motherboards and the CPUsets" on page 2-13.
- Time-out on the device bus.
- Post-write buffer.
- **■** Error state registers.

## 2.2 Local I/O Devices

Each motherboard has two PCI buses to handle local I/O - Bus0 and Bus1

### PCI Bus 0

- 10BaseT/100BaseTx Ethernet port 0 (CAF)
- PCI connection for DUART console and modem ports
- UltraSCSI controller for six-slot disk chassis (DSK)
- Four PCI card carrier slots (PCI4 to PCI7).

### PCI Bus 1

- 10BaseT/100BaseTx Ethernet port 1 (CAF)
- UltraSCSI controller for removable media module (RMM)
- Four PCI card carrier slots (PCI0 to PCI3).

# 2.3 Interrupts

Possible sources of interrupts on the motherboard are:

- SCSI one from each of the SCSI controllers
- Ethernet (PCIO) one from each
- DUART (console and modem)
- PCI slots (one per slot)
- Bridge error
- Motherboard mailbox one per CPUset
- Maintenance bus (environmental and insertion).

Each PCI slot has four interrupt signals which are combined to give one interrupt per slot. All these interrupts are concentrated into a six-bit code which is transmitted to the U2P ASIC in the CPUset (see Section 3.5.4 "U2P" on page 3-9) which connects to that motherboard. The same six-bit code is sent to both CPUsets.

There are two further interrupts, one per bridge, which are EState interrupts and route directly to the CPUsets.

## 2.4 Clock Generation

The master clock, running at 24.625 MHz, is on Motherboard B. Motherboard A synchronizes to a clock provided from Motherboard B. Each motherboard provides a clock to its local CPUset. If the clock on Motherboard B is lost, the clock on Motherboard A will not drift more than 100ppm. This means that Motherboard B can be replaced without large phase changes.

An indication is provided that the motherboard clocks are locked to each other (see Section 2.10 "LEDs and Indicators" on page 2-14).

If any PLLs lose lock, the system will move to the error state.

## 2.5 Maintenance Buses

There are two maintenance buses on each motherboard, one main maintenance bus and one alternate maintenance bus, making a total of four in the system.

### 2.5.1 Main Maintenance Bus

The main maintenance bus has sixteen segments, with the devices shown in TABLE 2-1.

TABLE 2-1 Main Maintenance Bus

Bus segment	Device	Purpose
Motherboard EEPROM Module information		Module information and status log
	Bit I/O	Fault LED
	Bit I/O	Injection interrupts
	Bit I/O	Module FET status
	LM75	Ambient temperature
	Bit I/O	PSU control
	Bit I/O	UPS status
CPUset	EEPROM	Module information and status log
	Bit I/O	Fault LED, power control, force fans

 TABLE 2-1
 Main Maintenance Bus (Continued)

Bus segment	Device	Purpose	
	LM78	Ambient temperature, fan monitor, processor temperature	
PCI slots (8)	EEPROM	Module information and status log	
	Bit I/O	Fault LED, power control, power monitor, presence bits	
	LM75	Ambient temperature	
CAF	EEPROM	Module information and status log	
	Bit I/O	Fault LED, power control, force fans, alarm port	
	LM78 (2)	Ambient temperature, fan monitor	
Drive chassis	EEPROM	Module information and status log	
	Bit I/O	Drive chassis: Fault LED, power control, injection monitor	
	Bit I/O (6)	Drive: Fault LED, power control	
	LM75	Ambient temperature	
RMM	EEPROM	Module information and status log	
	Bit I/O	Fault LED, power control, force fans	
	LM78	Ambient temperature, fan monitor	
PSU (3)	EEPROM	Module information and status log	
	Bit I/O	Fault LED, force fans, status	
	Bit I/O	Status	
	LM78	Ambient temperature, fan monitor, heatsink temperature, current monitor	

#### 2.5.2 Alternate Maintenance Bus

The alternate maintenance bus connects to devices on the other motherboard. The connection is carried by both CPUsets in parallel. On the other motherboard, the alternate maintenance bus connects to an 8574 Bit I/O device which controls an analog multiplexer to select and enable one of four maintenance bus segments, as shown in TABLE 2-2.

TABLE 2-2 Alternate Maintenance Bus Segments

Bus segment	Device	Purpose
Motherboard	EEPROM	Module information and status log
	Bit I/O	Fault LED
	Bit I/O	Injection interrupts
	Bit I/O	Module FET status
	LM75	Ambient temperature
	Bit I/O	PSU control
	Bit I/O	UPS status
CPUset Alternate Bus	Bit I/O	Power control
PSU (3)		Connects to the main maintenance bus segment on each PSU

The alternate maintenance bus has two purposes:

- To provide a second path to turn off a malfunctioning CPUset.
- To allow access to information about the status of PSUs when they are not functioning.
- To obtain history information from an unpowered motherboard during and after replacement.

The alternate maintenance bus is not intended to be used in the normal course of events, but only when the main maintenance bus is unusable.

### 2.6 Remote Control Processor

The Remote Control Processor (RCP) is a functional block that forms part of the Netra ft 1800 motherboard and which:

- Provides two serial ports (N,8,1,9600).
- Provides a multiplexed serial peripheral interface (SPI).
- Provides a field programmable gate array (FPGA) programming interface.
- Includes a motherboard power monitor with reset output to motherboard and reset input from motherboard.
- Qualifies two external pulsed reset signals.
- Polls the OSdog signal and the AC\_OK signal from the UPS interface.

The RCP provides a means of controlling the power supplies in the Netra ft 1800 system using commands sent via either of the two serial ports or the SPI (see Section 2.6.3 "SPI" on page 2-11).

An input is provided for the OSdog signal which is polled for a change of state. When this is detected it causes the PSU to be cycled.

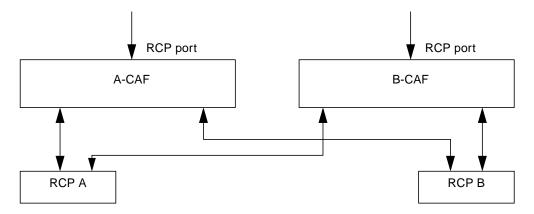


FIGURE 2-2 Remote Control Processor Signaling

### 2.6.1 RCP Serial Ports

The RCP is equipped with two serial ports. One is internal to the microcontroller and the other is an external DUART. The communications protocol is N,8,1,9600, and the pinout for both ports is shown in TABLE 2-3

TABLE 2-3 RCP Serial Connector Pinout

Pin	Function	I/O	Signal Description
2	TxD	O	Transmit Data
3	RxD	I	Receive Data
5	Sref		Signal Reference
Shell	Gnd		Chassis ground

### 2.6.2 RCP Commands

Case is important; the commands are based on a mask of two uppercase letters followed by a maximum of four lowercase letters. The following paragraphs describe these commands.

When commands are entered:

- All characters are considered. White space within address or command strings causes an error.
- The RCP will not respond to a carriage return or line feed that does not have any preceding characters.
- A command preceded by additional characters (for example, xxxAAres instead of AAres) will be considered invalid.
- A carriage return or line feed, or both in either order, denotes the termination of a command.
- Only one command can be given at a time a carriage return and/or line feed must follow each command.
- The RCP will echo commands once parsed, whether or not the parsing was successful, unless the buffer overflows. If the parsing is unsuccessful, the echoed command is followed by a question mark (?).

### 2.6.2.1 Motherboard Reset

Each RCP receives two active low external reset signals from the Alarm connector on its associated CAF. These are handled separately and must be greater than 200 ms and less than 300 ms in length. On receipt of a valid external reset signal, the RCP resets its motherboard with a 250 ms pulse.

If a motherboard is reset, the CPUset attached to that side is also reset; the effect is that the entire side is reset.

#### AAres

This command causes the Side A RCP to reset its motherboard. The reset pulse generated is 250 ms, and the command format is:

# AAres

#### BBres

This command causes the Side B RCP to reset its motherboard. The reset pulse generated is 250 ms, and the command format is:

# BBres

#### Power On/Off Motherboards 2.6.2.2

The RCP has two active low outputs which are used to instruct the PSUs to turn their output on or off. The RCP generates an output pulse in the range 45 to 50 ms in response to commands received via the UARTs or SPI.

#### AAon

This command causes the side A RCP to generate an active low pulse on its ON output which causes the PSU to apply power to the side A motherboard. Note that if the power on is successful, the RCP will hold the motherboard in reset while it configures the FPGAs.

### BBon

This command causes the side B RCP to generate an active low pulse on its ON output which causes the PSU to apply power to the side B motherboard. Note that if the power on is successful, the RCP will hold the motherboard in reset while it configures the FPGAs.

### AAoff

This command causes the side A RCP to generate an active low pulse on its OFF output which causes the PSU to remove power from the side A motherboard. If the RCP is configuring the FPGAs when this command is issued, it will abort the

### BBoff

This command causes the side B RCP to generate an active low pulse on its OFF output which causes the PSU to remove power from the side B motherboard. If the RCP is configuring the FPGAs when this command is issued, it will abort the process.

#### 2.6.2.3 Request Status

Refer to Appendix A "RCP Status Information" for a description of the status information.

### AAstat

This command is used to request the latest status information from the RCP. The returned data is an ASCII hex encoded version of the status information supplied by the RCP to the CPUset via the SPI. The order of the data is the same.

### **BBstat**

This command is used to request the latest status information from the RCP. The returned data is an ASCII hex encoded version of the status information supplied by the RCP to the CPUset via the SPI. The order of the data is the same.

#### 2.6.3 SPI

The SPI has two modes of operation:

■ RCP Program Download.

In order to download the RCP firmware, the CPUset must hold the RCP in reset. In this condition, the RCP recognizes a three-byte protocol.

Half duplex.

The normal communication mode between the RCP and the CPUset.

#### 2.6.4 Watchdog

The RCP has its own watchdog, which is kept awake by the main RCP program. If the RCP program fails, the watchdog is timed out and the RCP is reset. There is no effect on other hardware if this occurs.

#### 2.6.5 **RCP** Reset

The RCP can be reset from three sources: the CPUset, the watchdog, and its own power-on reset circuit. The CPUset holds the RCP in reset while it downloads new firmware to the microcontroller.

On leaving reset from either source, the RCP configures itself but does not reset the motherboard or attempt to configure the FPGAs. When the RCP is in reset, the reset signal to the motherboard is not asserted.

#### 2.6.6 **Power Monitor**

A monitor is provided that detects the presence of motherboard power. This monitor is polled by the RCP firmware.

### FPGA Setup and Data Storage 2.6.7

The FPGAs on the motherboard are daisychained so that each is programmed in turn from a single continuous data stream. The detection of a power up of the motherboard is the trigger event that causes the FPGAs to be configured.

On completion of the download, the RCP waits for a minimum of 10 µs before releasing the motherboard reset.

The FPGA is held in a flash memory device.

#### 2.6.8 **LED Indicators**

A green LED flashes when the RCP is running (see FIGURE 2-3 on page 2-15, FIGURE 2-4 on page 2-16 and Section 2.10 "LEDs and Indicators" on page 2-14).

## 2.7 Motherboard Controller

The motherboard controller provides the following registers:

- Determination of which CPUset is the primary (including during recovery from EState)
- Recording of most recent reason for reset:
  - remote, requested by the RCP
  - OSdog
  - synchronization
  - clock
- Mailbox interruptor
- Power status
- PLL lock status
- PCI slot IRQ concentrator.

## 2.8 Motherboards and the CPUsets

Each PCI bridge on the motherboard takes in one PCI bus from each of the two CPUsets. These are compared and buffered in the PCI bridge, and produce a single output PCI bus which serves the four I/O slots of the hotPCI bus. The PCI comparator tolerates input from the CPUset on the other side when the comparator power is off, and never drives current into a CPUset which is switched off.

There are two bridges on each motherboard, comparing four (two from each side) CPUset buses and producing two hotPCI buses on each side.

Each hotPCI slot is isolated by FETs from the motherboard bus. This allows cold PCI cards to be used in the hotPCI slot with an adapter. Power is also switched to the PCI cards under software control. At power on, the hotPCI slots are all switched off, and software enables them.

The PCI bridge logic allows CPUsets to access each others' address space. A mailbox facility is provided to allow one side to generate interrupts to the other side.

Both CPUsets are 'active' when running in fault tolerant configuration. All signals are compared on the bridges when appropriate.

### **Alarms** 2.9

The alarms function is handled by the motherboard controllers, one on each motherboard.

Two of the alarms registers on the motherboard controller are the 'pat' register, which controls the System LED on the CAF, and the general purpose alarms register which controls the user-definable alarm LED indicators via relays in the CAFs.

### 2.10 LEDs and Indicators

Refer to FIGURE 2-3 on page 2-15 and FIGURE 2-4 on page 2-16.

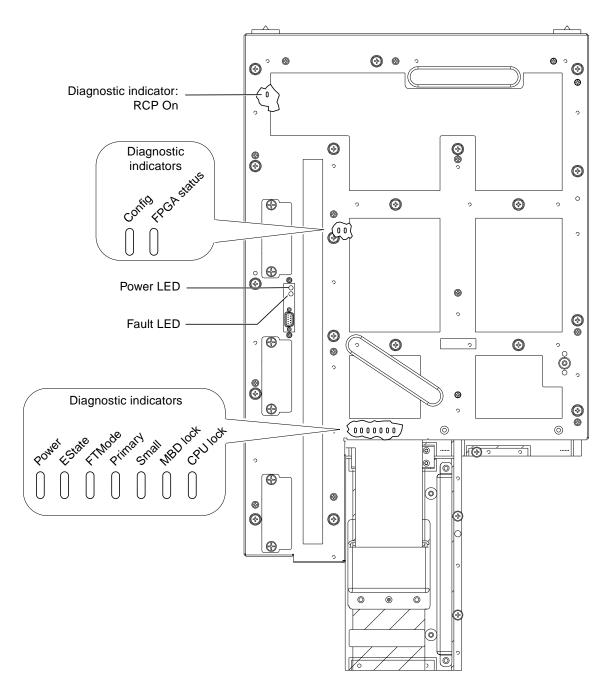


FIGURE 2-3 Upper Motherboard (A-MBD) LEDs and Diagnostic Indicators

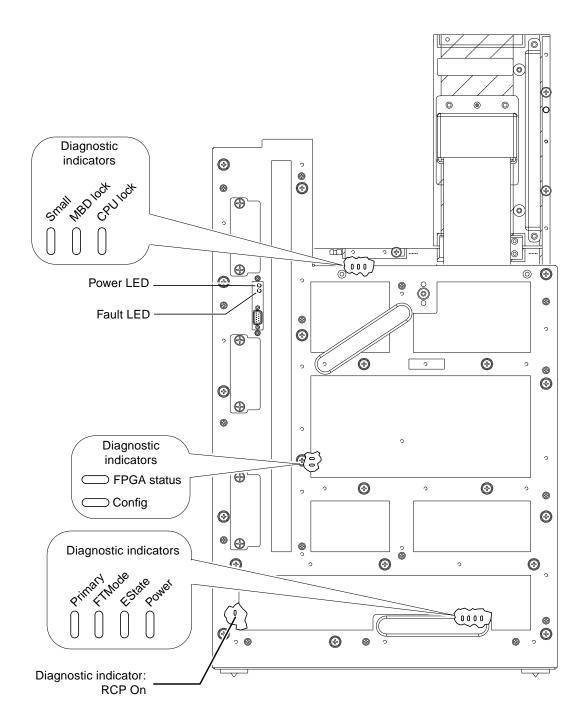


FIGURE 2-4 Lower Motherboard (B-MBD) LEDs and Diagnostic Indicators

#### 2.10.1 **LEDs**

The Power and Fault LEDs are always visible, and are repeated on the front of the appropriate CAFs.

### 2.10.2 **Diagnostic Indicators**

The motherboards incorporate a number of diagnostic indicators which are not generally visible when the covers are fitted. It is not necessary to view these indicators; motherboard status should only be established from the state of the Power and Fault LEDs on the motherboards or the repeaters on the CAFs.

These indicators and their functions are shown in TABLE 2-4.

TABLE 2-4 Motherboard Diagnostic Indicators

Name	Color	Meaning when lit	
Small	Green	Motherboard configured and ready.	
MBD Lock	Green	Both motherboards fitted and in lock.	
CPU Lock	Green	CPUset locked on to motherboard clock, and up and running.	
RCP On	Green flashing	RCP running. This will go out when the CPUset is downloading to the RCP internal flash PROM.	
EState	Red	Motherboard in EState, as after Reset, power-on or during error conditions.	
Config	Red	Motherboard faulty.	
FPGA Status	Red	FPGAs not loaded.	
Primary	Amber	Motherboard is <i>not</i> the active primary. One or both of these must be on. If both are off there may be a bridge interface error.	
FTMode	Amber	System in fault tolerant mode.	
Power	Green	Motherboard powered on.	

# **CPUsets**

The CPUset is the module that provides processing for a Netra ft 1800 system. A CPUset consists of one, two or four processor modules and associated connections and fans. Two CPUsets operating in lock-step form the 'core' of a fault tolerant system.

A CPUset module can accommodate up to four UltraSPARC II processor modules. Cooling is via closely-coupled dedicated fans mounted internally. The front panel contains indicators as shown in FIGURE 3-2.

## 3.1 Dimensions

The overall dimensions of a CPUset module are 555 mm (h) x 380 mm (d) x 150 mm (w) (21.85 inches x 15 inches x 5.9 inches).

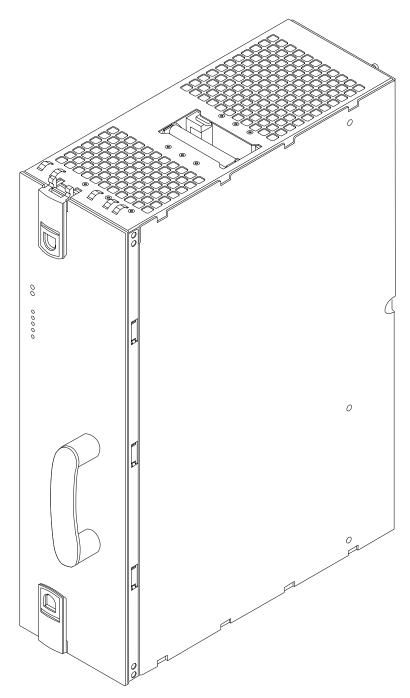


FIGURE 3-1 CPUset Module

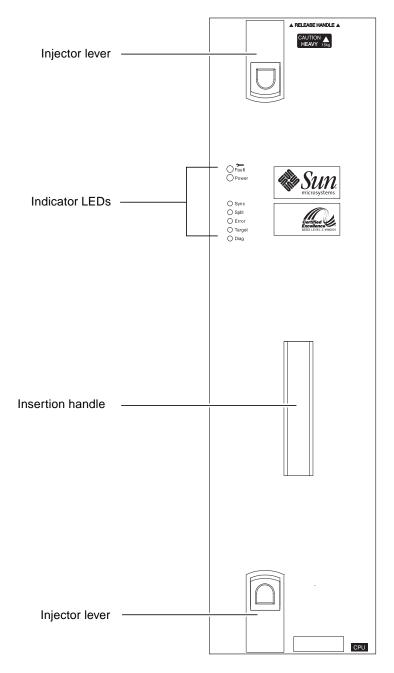


FIGURE 3-2 CPUset Front Panel

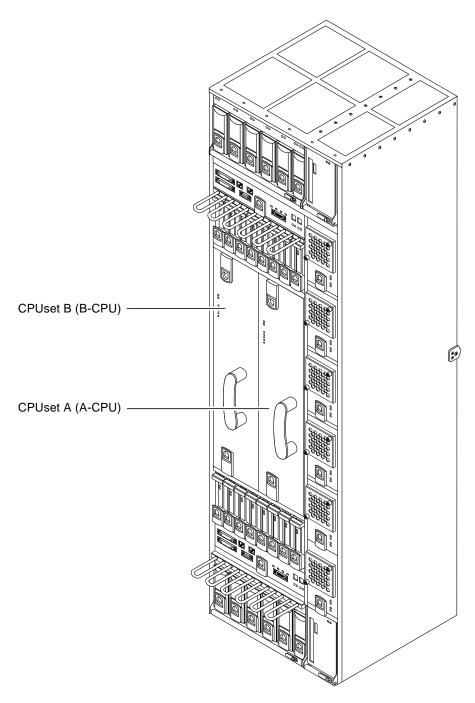


FIGURE 3-3 CPUset Locations

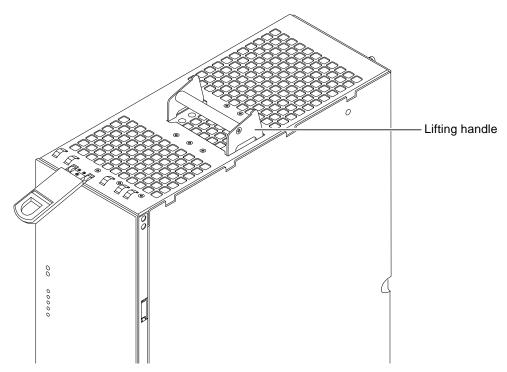


FIGURE 3-4 CPUset Lifting Handle Location

## 3.2 The CPUset

The CPUset module plugs into one of the two dedicated CPUset locations in the center of the main cabinet. With the other CPUset, it forms the self-checking and self-correcting core of the fault tolerant system.

The CPUset has the following features:

- One to four processor modules.
  - Each processor module contains one UltraSPARC II processor with parity protected secondary cache and ECC protected main bus. Both CPUsets must be configured identically in terms of number of processors, memory and firmware.
- Up to 4 Gbytes of ECC DRAM provided by 16 DIMM slots. Available configurations are:
  - 256 Mbytes (four x 64 Mbyte DIMMs).
  - 512 Mbytes (eight x 64 Mbyte DIMMs).

■ 4 Gbytes (16 x 256 Mbyte DIMMs).

The memory can be 1-, 2- or 4-way interleaved to provide up to 1.6 Gbyte/sec. peak memory bandwidth. The minimum memory size and increment is 256 Mbytes (four SIMMs).

- Flash PROM accessed through the Ebus2 interface provided by a PCIO ASIC.
- One to four power regulators, one per processor.
- Maintenance bus slave interface including EEPROM, temperature sensors and fan control and status.

The temperature of each processor is monitored.

- The standard Power and Fault LEDs.
- Five additional 3 mm LEDs.

See Section 3.3 "CPUset LEDs" on page 3-7.

- 8 Kbyte NVRAM/RTC and 32 Kbyte NVRAM.
- Two U2P controllers providing four motherboard PCI buses on each side, and an additional U2P controller to access the boot PROM.
- An SC\_MP system controller.
- Nine BMX+ crossbar switch slices to multiplex the multiple UPA buses.
- Clock generator circuitry generating phase-accurate multiples of the PCI input clock for the UPA, processor and U2P clocks.
- Two variable-speed fans.

# 3.3 CPUset LEDs

In addition to the standard *Power* and *Fault* LEDs described in Section 1.4.2 "LED Indicators" on page 1-4, the CPUset has five 3 mm amber LEDs as described in TABLE 3-1.

TABLE 3-1 CPUset Indicator LEDs

Indicator	Meaning	
Sync	CPUset is running in synchronization with the other	
Split	CPUset is running in split mode	
Error	CPUset is in an error state	
Target	CPUset is the target of processor re-integration	
Diag	Lit by any reset; flashes when Solaris is running	

# 3.4 Clock Generation

TABLE 3-2 shows the different clock domains on the CPUset.

TABLE 3-2 Clock Domains on the CPUset

Clock	Relationship to PCI clock frequency
U2P Reference Clock	PCI
U2P Clock	2*PCI
UPA Clock	4*PCI
CPU Clock ≤ 300 MHz	6*PCI
CPU Clock > 300 MHz	8*PCI

## 3.5 Processors and ASICs

As well as the use of UltraSPARC II processors, the system unit achieves a high level of integration through application-specific integrated circuits (ASICs). With the exception of the BMX+ ASIC, all ASICs are IEEE 1149.1 (JTAG) compliant. The ASICs are:

- Crossbar switch (BMX+)
- PCI-to Ebus/Ethernet controller (PCIO)
- UPA-to-PCI bridge (U2P).

### 3.5.1 UltraSPARC II Processor

The UltraSPARC II processor is a high-performance, highly integrated super-scalar processor implementing the SPARC-V9 64-bit RISC architecture. The UltraSPARC II processor is capable of sustaining the execution of up to four instructions per cycle even in the presence of conditional branches and cache misses. This sustained performance is supported by a decoupled prefetch and dispatch unit with instruction buffer.

UltraSPARC II processor characteristics and associated features include:

- SPARC-V9 architecture compliance
- Binary compatibility with all SPARC application code:
  - Multiprocessing support
  - Glueless four-processor connection with minimum latency
- Snooping or directory-based protocol support
- Four-way superscalar design with nine execution units
- Four integer execution units
- Three floating-point execution units
- Selectable little- or big-endian byte ordering
- 64-bit address pointers
- 16Kbyte non-blocking data cache
- 16Kbyte instruction cache
- Single cycle branch following
- Power management
- Software prefetch instruction support
- Multiple outstanding requests.

#### 3.5.2 BMX+

The crossbar switch (BMX+) ASICs form the hub of all data transfers in the system unit. The BMX+ ASIC permits the implementation of a high bandwidth interleaved dual bank memory system. It coordinates between memory (two buses, each 576 bits wide), the two processor UPA buses (144 bits wide) and the I/O UPA bus (72 bits wide). Data transfers take place between any of the ports, bit-sliced into nine parts, all of which are required to implement a full connection.

#### 3.5.3 **PCIO**

The PCI-to-Ebus2 controller (PCIO) ASIC performs PCI bus-to-Ebus2 bridging and provides the electrical connection to slower on-board functions, such as the Flash PROM and the alarms module.

#### 3.5.4 U2P

The UPA-to-PCI bridge (U2P) ASIC provides an I/O connection between the UPA bus and the two PCI buses. The U2P ASIC features include:

- Full master and slave port connection to the high-speed UPA interconnect The UPA is a split address/data packet-switched bus that has a potential data throughput rate greater than 1 Gbyte/second. UPA data is ECC protected.
- Two 25 MHz PCI bus segments: 5.0 Vdc signaling, 64-bit data bus.
- Two separate 16-entry streaming caches, one for each bus segment, for accelerating some kinds of PCI DVMA activity.
  - Single IOMMU with 16-entry TLB for mapping DVMA addresses for both buses (IOMMU used to translate 32- or 64-bit PCI addresses into 41-bit UPA addresses).
- A mondo-vector dispatch unit for delivering interrupt requests to the CPUset module, including support for PCI interrupts from up to six slots, as well as interrupts from on-board I/O devices.

Three U2P ASICs are used in the CPUset:

- One for access to on-board devices (PROM, NVRAM etc.)
- Two, for connection to the motherboards (one to each).

### **UPA** 3.6

The UltraSPARC port architecture (UPA) provides a packet-based interconnection between the UPA clients—CPU modules and U2P ASIC. Electrical interconnection is provided through three address buses and four data buses.

### The three address buses:

- UPA address bus 0 (UPA\_AD0) Processor 0+1
- UPA address bus 1 (UPA\_AD1) Processor 2+3
- UPA address bus 2 (UPA\_AD2) U2P A,B+C

### The four data buses:

- UPA data bus 0 (UPA\_DATA0) Processor 0+1
- UPA data bus 1 (UPA\_DATA1) Processor 2+3
- UPA data bus 2 (UPA\_DATA2) U2P A+C
- UPA data bus 3 (UPA\_DATA3) U2P B

### Refer to FIGURE 3-5.

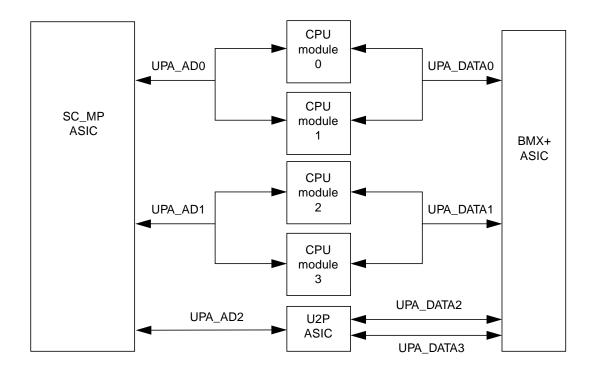


FIGURE 3-5 Data Buses on a CPUset

UPA\_AD0, UPA\_AD1 and UPA\_AD2 are full 36-bit bidirectional buses that connect the SC\_MP ASIC to the CPU modules and the U2P ASICs. UPA\_DATA0 and UPA\_DATA1 are bidirectional 144-bit data buses (128 bits of data and 16 bits of ECC) that connect the CPU modules to the BMX+ ASIC. UPA\_DATA2 and UPA\_DATA3 are bidirectional 72-bit data buses (64 bits of data and eight bits of ECC) that connect the U2P ASIC to the BMX+ ASIC.

FIGURE 3-5 illustrates how the UPA address and data buses are connected between the UPA and the UPA clients.

## 3.7 PCI Buses

The peripheral component interconnect (PCI) bus is a high-performance 32- or 64-bit bus with multiplexed address and data lines. The PCI bus provides electrical interconnect between highly integrated peripheral controller components, peripheral add-on devices, and the processor/memory system.

## 3.7.1 **U2P ASIC**

The UPA-to-PCI bridge (U2P) ASIC controls the PCI buses. It forms the bridge from the UPA bus to the PCI buses. For a brief description of the U2P ASIC, see Section 3.5.4 "U2P" on page 3-9.

### 3.7.2 PCIO ASIC

The PCI-to-Ebus/Ethernet controller (PCIO) ASIC bridges the PCI bus to the Ebus, enabling communication between the PCI bus and all miscellaneous I/O functions as well as the connection to slower on-board functions. For a brief description of the PCIO ASIC, see Section 3.5.3 "PCIO" on page 3-9.

## CHAPTER 4

# Mass Storage

The mass storage hardware consists of a drive chassis (DSK) that contains up to six hard disk drive (HDD) modules. Both the chassis and the individual disk modules are hot-insertable. Fast-20 (Ultra-SCSI) transfers are supported.

The overall dimensions of the disk chassis are 310 mm (w) x 385 mm (d) x 175 mm (h) (12.20 inches x 15.16 inches x 6.89 inches).

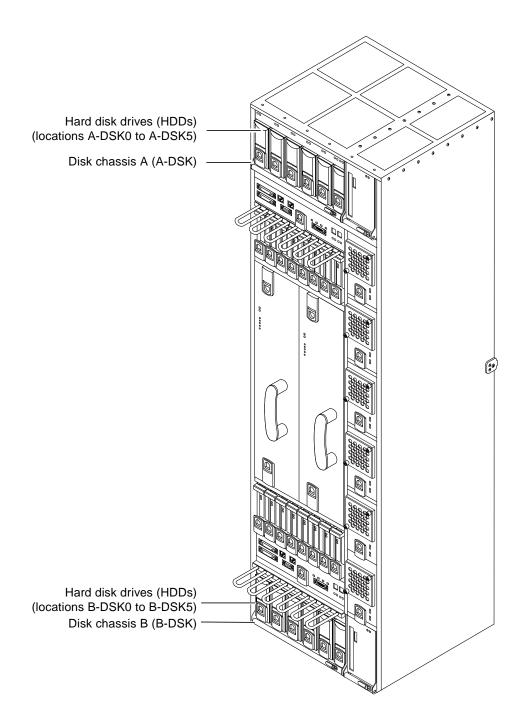


FIGURE 4-1 Disk Chassis Locations

# 4.1 Drive Chassis

The drive chassis accommodates up to six standard Fast-20 (UltraSCSI) 3.5-inch disks in a special shielded bracket assembly forming modules with integral ejectors that directly connect to a dedicated SCSI backplane. The chassis has associated *Fault* and *Power* indicators as described in Section 1.4.2 "LED Indicators" on page 1-4. There are also *Fault* and *Power* LEDs above each disk slot.

The chassis contains four boards:

- Backplane
- Adapter board
- Power board
- LED board.

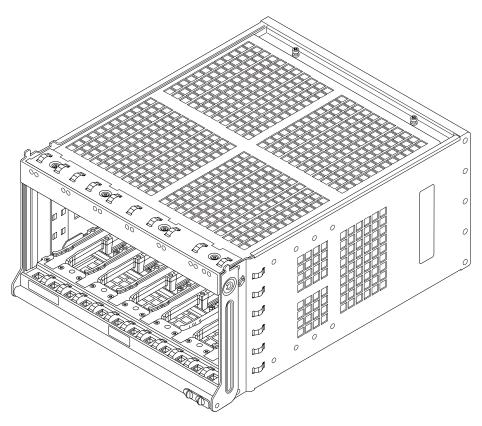


FIGURE 4-2 Disk Drive Chassis (no drives fitted)

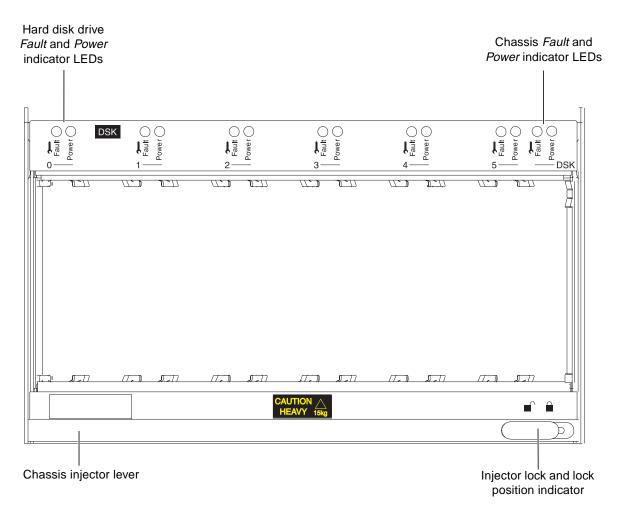


FIGURE 4-3 Disk Chassis Front Panel

# 4.2 Hard Disk Drives

The disk drives are Fast-20 (UltraSCSI) compatible.

Disk drives are fully hot-insertable, with no need to quiesce the SCSI bus. The disks do not have maintenance buses for serial numbers and history. The disks are mounted on EMC-compliant carriers which provide physical location of the drives only, and do not support maintenance bus access.

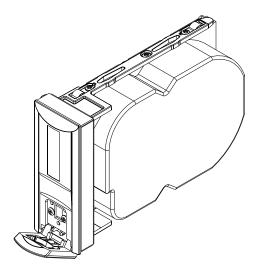


FIGURE 4-4 Hard Disk Drive Module

The disk injectors do not control power supply. A disk is powered as soon as it is fully inserted into the disk chassis.

Fault tolerance is achieved using the disk drives as mirrored pairs, with the drives in each pair normally fitted to opposite sides of the machine in corresponding slots. This mirroring is enforced entirely by the Volume Manager software. See the *Netra ft 1800 User's Guide.* 

When a new disk is enabled, the mirroring software copies data from the other half of the pair to the new disk while maintaining normal system operation. To improve disk data error detection, disk checksums can be calculated and checked under CMS control, during reads.

In the disk subsystem, latent fault checking is provided by a user process which runs continuously, exercising all parts of the disks. This process is configurable to check all the disks.

# Removable Media Modules

A removable media module (RMM) contains one or two standard 8-bit half-height 5.25 inch SCSI-2 devices mounted side by side. The module is hot-replaceable, and contains *Fault* and *Power* indicators as described in Section 1.4 "Common Features of Modules" on page 1-4. The module also contains a fan to assist in cooling the PSU modules.

The overall dimensions of an RMM module are 105 mm (w) x 385 mm (d) x 175 mm (h) (4.13 inches x 15.16 inches x 6.89 inches).

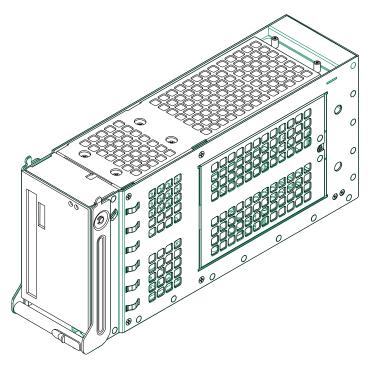


FIGURE 5-1 RMM Drive Chassis (CD-ROM-only Configuration)

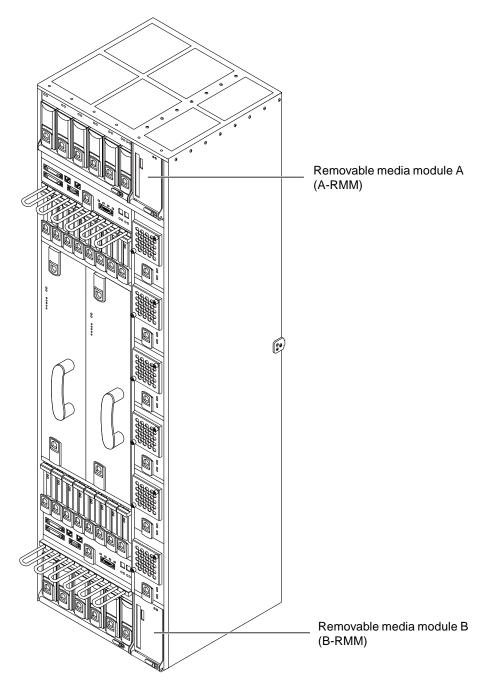


FIGURE 5-2 Disk and RMM Chassis Locations

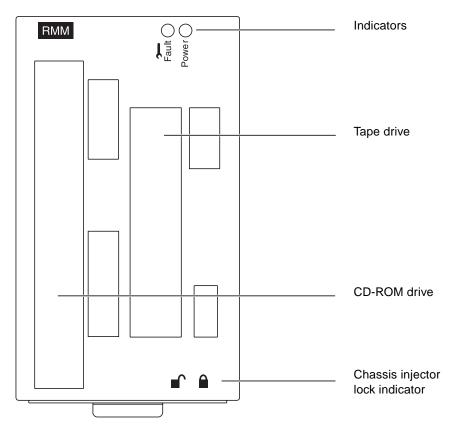


FIGURE 5-3 RMM Drive Chassis Front Panel (CD-ROM and DAT Tape Configuration)

The drives are permanently installed in the module, and the entire module is swapped as a hot-replaceable unit. The two slots are normally occupied by a CD-ROM and a tape drive. The tape drive can be omitted. The SCSI bus connects to a dedicated SCSI controller on the motherboard.

The system must always contain two RMM modules to ensure adequate cooling, even if one of the modules contains no drives.

# Console, Alarms and Fans

The console, alarms and fans (CAF) module provides the standard system I/O interfaces, accessible from the front of the system.

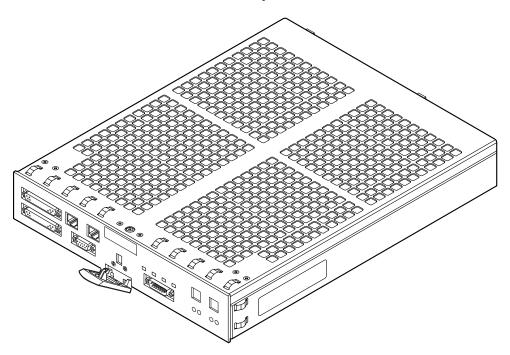


FIGURE 6-1 Console, Alarms and Fans Module

The overall dimensions for a CAF module are 305 mm (w) x 385 mm (d) x 58 mm (h) (12 inches x 15.16 inches x 2.29 inches).

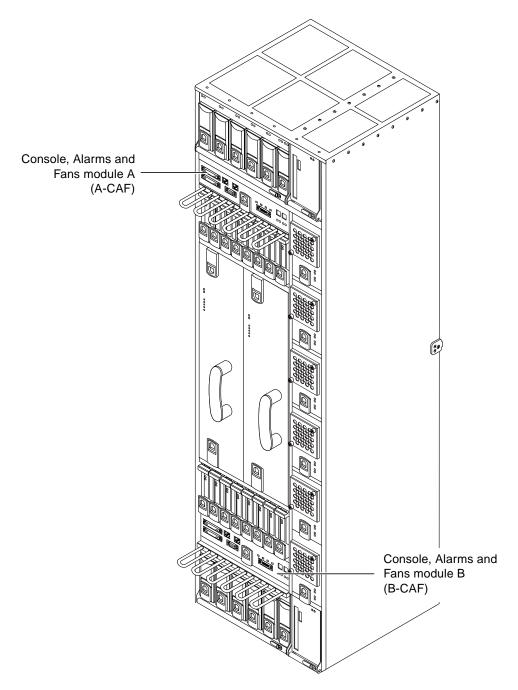


FIGURE 6-2 CAF Module Locations

The CAF module contains the following on its front panel (see FIGURE 6-3):

- One green *System* indicator.
- Three amber user-defined *Alarm* indicators.
- Fault and Power indicators for the CAF.
- *Fault* and *Power* indicators for the motherboard (repeaters).
- Power *On* and *Stby* switches.
- Alarm relays and timed resets.
- **■** Two Ethernet interfaces.
- Modem port.
- Console port.
- RCP port.

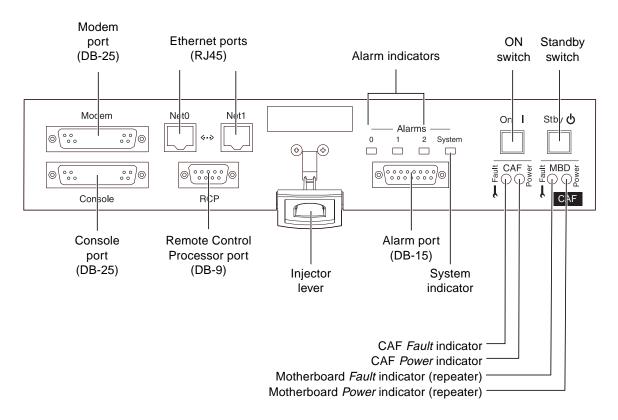


FIGURE 6-3 CAF Module Front Panel

# 6.1 Power Controls and Supply

The power *On* and *Stby* switches are momentary push-buttons which control power to the motherboard on the same side of the machine as the CAF module.

- The *On* switch is green. When pressed, it turns on the power supplies on that side.
- The *Stby* switch is black. When pressed, it turns off the power supplies on that side. It does not isolate the system. (External circuit breakers are required to do this.)

The CAF is supplied with a +14V rail via the motherboard. The +14V rail is controlled by means of an electronic cut-out on the motherboard which is enabled by the injector switch. If the cut-out is tripped by a fault condition, the injector must be opened to reset it.

The local maintenance bus +5V rail is separately supplied, so that providing the module is injected, some maintenance bus devices remain accessible even during a fault condition.

The CAF has a secondary DC-DC converter that provides +5V to the Ethernet circuitry. The converter is off by default.

The four fans in the CAF are individually supplied directly from the +14V input and their start-up is staggered.

The motherboard standby voltage goes to the CAF to power the RCP RS232 devices, so that the RCP is still accessible even when the motherboard is powered off.

# 6.2 Alarm Relays and Timed Resets

The alarm relays are driven by signals generated on the active motherboard. The relay contacts can carry up to 100 Vdc or 1A with a maximum rating of 30 W/30VA.

Both normally-open and normally-closed contacts are provided, except on the GP2 alarm, where normally-open contacts only are provided.

The *System* relay is hard-wired to a watchdog associated with that side of the machine. (Note that this watchdog is different from the OSdog.) This alarm can be forced by software (CMS) to the on (alarmed) state, but can be set to the off state only by the watchdog. The front-panel *System* indicator illuminates automatically when the system relay is in the off (non-alarmed) state.

The remaining three alarms in each group are entirely under software control and default to the non-alarmed state when powered-on and not initialized; they also assume the non-alarmed state when power is removed.

The timed-pulse reset inputs are accessible on the same connector as the alarm relays. There are two timed reset input signal pairs. Each pair consists of a signal (RESET+) plus return (RESET-). Both pairs are optically isolated from the reset of the system. The timed reset pulse is generated by asserting a signal on RESET+ of greater than 3.3V with respect to RESET-. The acceptable voltage range of this input is 3.3V to 48V continuous, and up to 60V at a 50% duty cycle. The current drawn by the input is in the range 3mA to 12mA approximately. If the polarity of the connections is reversed no damage will result. The pulse should last between 200ms and 300ms.

The three general-purpose alarm indicators illuminate automatically when their corresponding relays are in the on (alarmed) state.

Connection is via a male DB-15 with pinout as shown in TABLE 6-1.

TABLE 6-1 Alarm Port Pinout

Pin	Description	Pin	Description
1	RESET0+	9	ALARM0-NC
2	RESETO-	10	ALARM0-COM
3	RESET1+	11	ALARM1-NO
4	RESET1-	12	ALARM1-NC
5	SYSTEM-NO	13	ALARM1-COM
6	SYSTEM-NC	14	ALARM2-NO
7	SYSTEM-COM	15	ALARM2-COM
8	ALARMO-NO		

## 6.3 Serial Interfaces

The following serial interfaces are provided:

- Console port
- Modem port
- RCP port.

All of the serial ports are isolated from the rest of the system using optocouplers and an isolating DC-DC converter. These are all located in the CAF module and provide at least 500 Vdc isolation. The RS232 drivers and ESD and EMC protection components are all located in the CAF module.

The DC-DC converter is powered from the standby +5V supply. This means that, provided a PSU is inserted on the same side, the RCP serial port is functional at all times.

In combined (fault tolerant) mode, output characters are written to the console ports on both sides of the machine by default, and to the modem ports if DCD is asserted. Input characters from both console ports are merged, along with input characters from both modem ports if DCD is asserted.

In split mode, output characters are sent only to the console port on the same side of the machine, and are echoed to the modem port if DCD is asserted. Input characters are taken from this console port, and are merged with input characters from the modem port if DCD is asserted.

To provide for split operation, the console and modem ports from both sides are brought to separate dedicated connectors, one connector per side.

The serial ports are opto-isolated and are protected from ESD.

### 6.3.1 Console Port

The console connection in the CAF is an RS232 port communicating with the motherboard UART. Connection is via a female DB-25 whose pinout is shown in TABLE 6-2.

TABLE 6-2 Console Connector Pinout

Pin	Function	Description
1	GND	Chassis ground
2	TxD	Output data
3	RxD	Input data
7	SREF	Signal reference
Shield	hield Chassis ground	

The port is designed so that whatever external signals are presented, the port will continue normal operation after the external signals have returned to their normal state (provided that such signals stay within the RS232 electrical specification).

#### 6.3.2 **Modem Port**

The modem connection in the CAF is an RS232 port communicating with the motherboard UART. Connection is via a female DB-25 whose pinout is shown in TABLE 6-3.

TABLE 6-3 Modem Port Pinout

Pin	Function	Description
1	GND	Chassis ground
2	TxD	Output data
3	RxD	Input data
4	RTS	Output handshake
5	CTS	Input handshake
7	SREF	Signal reference
8	DCD	Input status
20	DTR	Output status
Shield		Chassis ground

The port is designed so that whatever external signals are presented, the port will continue normal operation after the external signals have returned to their normal state (provided that such signals stay within the RS232 electrical specification).

#### 6.3.3 **RCP Port**

There is an RS232 connection to the Remote Control Processor (RCP) on the motherboard. Connection is via a female DB-9 whose pinout is shown in TABLE 6-4.

TABLE 6-4 Remote Control Processor Port Pinout

Pin	Function	Description
2	TxD	Output data
3	RxD	Input data
5	SREF	Signal reference
Shield		Chassis ground

## 6.4 Maintenance Bus

The following maintenance bus functions are supported by the CAF module:

- Fault LED switching
- **■** Ethernet power control
- Temperature sensing
- History EEPROM
- Fan speed monitoring and testing (four fans).

## 6.5 Fans and Fan Control

The CAF module contains four large (120 mm) fans whose speed is controlled in the range 50% to 100% of maximum as the ambient air temperature increases over the range  $30^{\circ}$ C to  $45^{\circ}$ C. Controlling the speed of the fans both increases their life and reduces their noise level. The fans are monitored by two LM78 devices. Two fans are monitored by each device.

The fans are powered on one by one as soon as the CAF module is injected; this ensures there is no sudden power surge. They cannot be turned off by the maintenance bus.

### 6.6 Ethernet LAN Interfaces

The CAF contains a separate board providing two complete Ethernet physical layer interfaces. These interfaces connect to their motherboard MAC devices using Media-Independent Interfaces (MII) via the CAF baseboard. Each interface supports 10BaseT and 100BaseTx transfers in accordance with IEEE 802.3. Autonegotiation is supported.

The Ethernet board is provided with a dedicated, switchable +5V rail by a regulator located on the CAF baseboard. When this rail is operational, the *Power* indicator is illuminated on the CAF front panel.

#### 6.6.1 **Ethernet Interfaces**

Connection is via RJ45 jacks which have the pinout shown in TABLE 6-5.

**Ethernet LAN Connector Pinout** 

Pin	Function	Description
1	TX+	Transmit+
2	TX-	Transmit-
3	RX+	Receive+
6	RX-	Receive-
Shield		Chassis ground

Pins 4, 5 and 7, 8 are connected to a common-mode termination.

## **PCI** Modules

Standard PCI cards can be used in a Netra ft 1800 system when they are included in a PCI module. Supported cards are shown in TABLE 7-1. The PCI module consists of the card and a PCI carrier which has the standard features of a module.

The PCI carrier accommodates both short and long industry-standard PCI format interface cards, utilizing the ISA style I/O panel. I/O cabling access is via the front panel of this module. The module has an ejection system with an interlock switch as described in Section 1.4.4 "Module Injection Mechanisms" on page 1-6. The front panel contains indicators as described in Section 1.4 "Common Features of Modules" on page 1-4. The PCI carrier modules have no internal forced-air cooling, relying on the CAF module.

The overall dimensions of a PCI module are 142 mm (w) x 390 mm (d) x 34 mm (h) (5.5 inches x 14.6 inches x 1.34 inches).

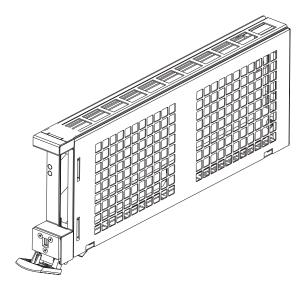


FIGURE 7-1 PCI Card Carrier

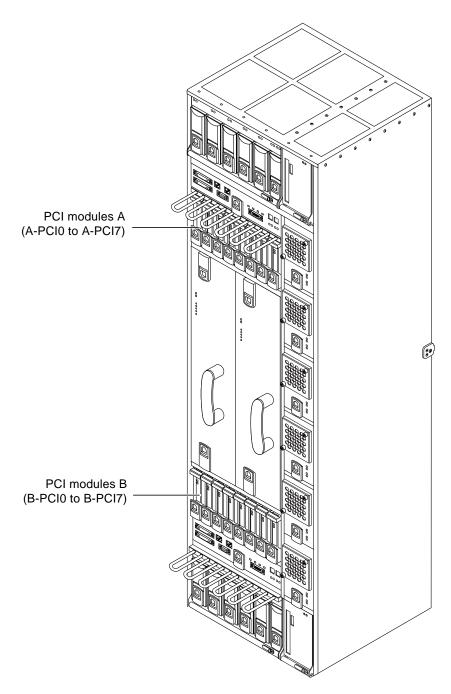


FIGURE 7-2 PCI Module Locations

### 7.1 **Supported Cards**

TABLE 7-1 shows the currently-supported PCI cards. Extra cables are provided for all but the ATM cards.

Supported PCI Cards TABLE 7-1

Туре	Name	Data Width
HSI	Hotplug PCI Carrier with High Speed Serial Interface Card	32-bit
$ATM^1$	Hotplug PCI Carrier with ATM 155Mb Card (MMF)	64-bit
SAI	Hotplug PCI Carrier with 8-Port Async Card	32-bit
Fast Ethernet	Hotplug PCI Carrier with 10/100BaseT Fast Ethernet Card	32-bit
UltraSCSI	Hotplug PCI Carrier with Dual Channel Differential2 Card	32-bit

<sup>1.</sup> Maximum of two per side.

Note - The Netra ft 1800 has a PCI clock speed of 25MHz.



**Caution** – The use of certain PCI cards can connect the Frame and Logic grounds (if they have been isolated by removal of the link on the rear of the chassis) and cannot be used in a dual grounding environment. Refer to the documentation supplied with each PCI card.

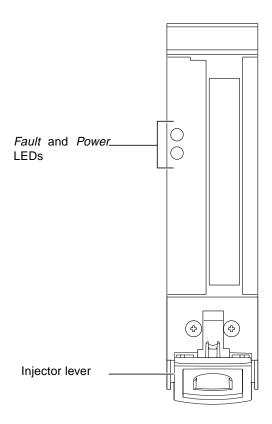


FIGURE 7-3 PCI Card Carrier Front Panel

## 7.2 Cabling

The SAI/P cable with box assembly supplied with the SAI PCI card must be secured entirely within the host rack. It is VW-1 rated cable, and as such must not be installed in vertical cable trays or routed from one rack/cabinet to another adjacent cabinet. I/O cables coming into the host frame to mate with the SAI/P breakout box must meet the applicable local fire codes (for example, have a CL2 or CM Listing mark denoting, among other things, that it complies with vertical-tray flame test requirements).

### 7.3 **Module Insertion**



**Caution** – It is important that care is taken when inserting PCI card carriers into the Netra ft 1800 chassis. The only alignment aids are the card guides at the top and base of the slots; the connectors on the rear of the cards are complex and fragile, and can be damaged if the cards are not inserted with care.

## **Power Supply Units**

Each side of a Netra ft 1800 system has locations for up to three power supply units (PSUs). The power supply unit (PSU) is a module based on a number of PCBs with all required heatsinking and a cooling fan mounted internally. The module has an injector/ejector with an interlocked switch as described in Section 1.4.4 "Module Injection Mechanisms" on page 1-6. The front panel contains indicators as described in Section 8.1.1 "Module LEDs" on page 8-3.

The overall dimensions of the PSU module are 97.8 mm (w) x 376 mm (d) x 161 mm (h) (3.4 inches x 14.1 inches x 6.3 inches).

For information about system and electrical installation, refer to the *Netra ft 1800 Installation Guide* (Part No. 805-4533-10).

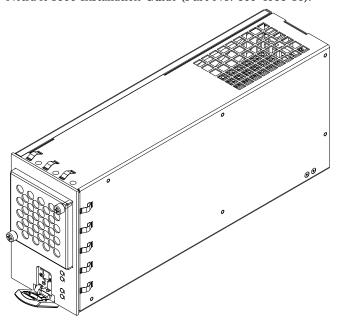


FIGURE 8-1 Power Supply Module

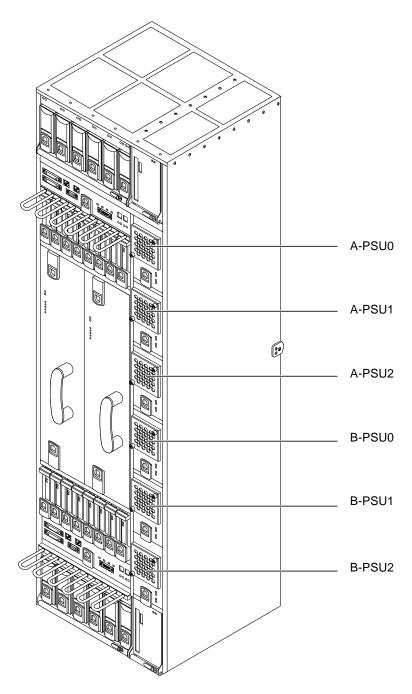


FIGURE 8-2 PSU Module Locations

### 8.1 –48V Dual Inlet PSU

External circuit breakers must be fitted in the customer frame before the -48V and return rails are supplied to the chassis.

The -48V PSU is front-replaceable. It has two diode-commoned -48V inputs, which are individually fused internally with voltage monitoring. The return rail of the two inputs is common.

The PSU is turned on and off by separate 'on' and 'off' inputs and remembers its state internally. The on and off inputs can be generated from the maintenance bus, the control panel On and Standby buttons or by the Remote Control Processor (RCP).

The PSU has three groups of output rails: one for the CPUset, one for the remainder of the system, and one for standby. The standby supply is always on when the injector is fully engaged and one of the –48V inputs is present. The standby supply powers the maintenance bus and the Remote Control Processor.

### 8.1.1 Module LEDs

There are four LED indicators on the front of each PSU. These have the following meanings:

- *Input Present A* (green), *Input Present B* (green)

  These are illuminated while the appropriate input voltages are present, regardless of whether the module has been switched on or off. The LEDs will go out when their respective DC input voltages are removed. When the module is removed from the chassis the LEDs will go out within one second.
- Power (green)

  This is illuminated when all requested outputs are functional within predefined parameters. If the CPUset is not requested to be enabled, the LED indicates the state excluding the CPUset-specific rails. The LED will go out within 200 ms of any failure.
- Fault (red)
  This is under the control of the maintenance bus, and will illuminate when the system believes the PSU to be defective.

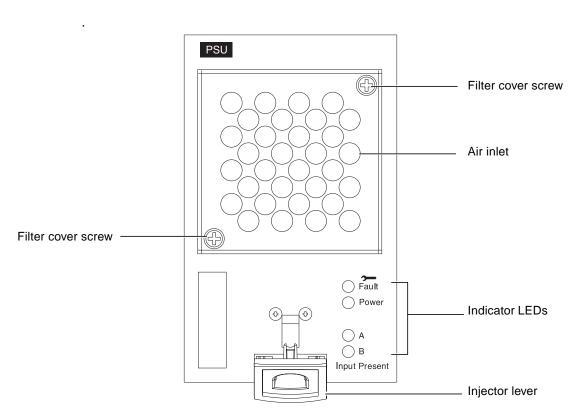


FIGURE 8-3 Power Supply Module Front Panel

# 8.2 DC Outputs

V1, V2 and V3a outputs can operate in a redundant current-sharing mode. A maximum of three power supply modules can be operated in parallel.

 TABLE 8-1
 Power Supply DC Output Ratings

Output	Voltage (V)	Current (A)	Power (W)
V1	+3.3	28	92
V2	+5	31	155
V3a	+14	17.7	248

TABLE 8-1 Power Supply DC Output Ratings (Continued)

Output	Voltage (V)	Current (A)	Power (W)
V3b	+14	5.0	70
V4	+5	8.0	40
V5	+5	1.0	5

#### 8.3 **Troubleshooting**

If the PSU has the condition offline, this indicates that the external power supply has failed. If the module cannot be re-enabled, carry out the following procedure before ordering a replacement module:

- 1. Ensure that the injector is fully engaged.
- 2. Check the circuit breaker. The actuator should be in the 1 position. Reset the circuit breaker as required.
- 3. Contact an electrician to confirm that the branch circuit is still energized. If the branch circuit is operational, contact your local support organization.

**Note** – If the PSU re-enables during any of these steps, it must be reconfigured. See the Netra ft 1800 User's Guide for information about configuring modules into the system.

### APPENDIX A

## **RCP Status Information**

TABLE A-1 describes the status data returned to the CPUset. The status information is accessed using the AAstat command via the serial ports, and is returned as an ASCII string. There are therefore 38 characters representing the 19 bytes. In this case the first two characters are 26 (= 38 decimal).

Status byte values are shown in TABLE A-2, TABLE A-3 and TABLE A-4.

TABLE A-1 RCP Status Information

Byte	Description
0	Length byte = 19 decimal
1	RCP firmware revision
2	RCP firmware checksum high
3	RCP firmware checksum low
4	FPGA0 revision
5	FPGA0 checksum high
6	FPGA0 checksum low
7	FPGA1 revision
8	FPGA1 checksum high
9	FPGA1 checksum low
10	FPGA2 revision
11	FPGA2 checksum high
12	FPGA2 checksum low
13	FPGA3 revision
14	FPGA3 checksum high
15	FPGA3 checksum low

 TABLE A-1
 RCP Status Information (Continued)

Byte	Description	
16	Status byte 0	
17	Status byte 1	
18	Status byte 2	

TABLE A-2 Status Byte 0

Bit	Description
0	FPGA0 download fail = 1
1	FPGA0 checksum fail = 1
2	FPGA1 download fail = 1
3	FPGA1 checksum fail = 1
4	FPGA2 download fail = 1
5	FPGA2 checksum fail = 1
6	FPGA3 download fail = 1
7	FPGA3 checksum fail = 1

TABLE A-3 Status Byte 1

Bit	Description
0	Motherboard power on = 1
1	Serial port 0 initiated power on = 1
2	Serial port 0 initiated power off = 1
3	Serial port 1 initiated power on = 1
4	Serial port 1 initiated power off = 1
5	Serial port 0 initiated motherboard reset = 1
6	Serial port 1 initiated motherboard reset = 1
7	RCP reset by watchdog = 1

TABLE A-4 Status Byte 2

Bit	Description
0	Timed reset0 = 1
1	Timed reset1 = 1
2	SPI command initiated power cycle = 1
3	SPI command initiated reset = 1
4	SPI command initiated FPGA download $+$ reset = 1
5	SPI command initiated AC recover = 1
6	OSdog barked = 1
7	Not used = 0

## Glossary

ASIC Application-Specific Integrated Circuit.

ASR Automatic System Recovery: reboot on system hang.

BMX+ Crossbar switch ASIC.

**bridge** The interface between the *CPUsets* and the I/O devices.

CAF Console. Alarms and Fans module.

CMS Configuration Management System. The software that records and monitors the *modules* in the system. Users access the CMS via a set of utilities which they use to add and remove modules from the system configuration and *enable* and

disable modules that are in the system configuration.

component An identifiable part of a module.

**configure** (*CMS*) Notify the CMS that a *module* is present in a specified location.

constituent (CMS) An object that provides part of the functionality of another object. An

object references its constituents.

**CPUset** A *module* containing the system processors and associated components.

craft-replaceable A module which clearly indicates when it is faulty and can be hot-replaced by a

trained craftsperson.

**DIMM** Dual Inline Memory Module.

disable (CMS). Bring offline and power down a module.

**DMA** Direct Memory Access.

**DRAM** Dynamic Random Access Memory.

DSK Disk chassis module.

**DVMA** Direct Virtual Memory Access. A mechanism to enable a device on the PCI bus

to initiate data transfers between it and the CPUsets.

**ECC** Error Correcting Code.

**EEPROM** Electrically Erasable Programmable Read Only Memory.

**EMI** Electro-magnetic Interference.

enable (CMS) Power up and bring online a module that is already configured into the

system.

**engineer-replaceable** A *module* which may not indicate that it is faulty and which may require

special tools for diagnosis and replacement. The Netra ft 1800 does not have

any engineer-replaceable modules.

ESD ElectroStatic Discharge.

**EState** Error limitation mode.

fault tolerant A system in which no single hardware failure can disrupt system operation.

**fault-free** No faults are evident in the operating system, or application software, or in

external systems, except in the case of certain high demand real-time uses.

faulty module A module one or more of whose devices have gone into the degraded or failed

states, as indicated to the CMS via the hot-plug device driver framework.

FPGA Field Programmable Gate Array.

**front-replaceable** The ability to replace a *module* from the front of the system.

**FRU** Field Replaceable Unit. Another name for a *module*, used within the *CMS*.

**HDD** Hard Disk Drive.

hardened Specially engineered to be resistant to hardware and some causes of software

failure. Applies to device drivers.

**health features** Features that can indicate that a fault is about to occur.

**hot plug** The ability to insert or remove a *module* without causing an interruption of

service to the operating platform.

hotPCI An implementation of the PCI bus designed to minimize the probability

that a fault on a *module* will corrupt the bus, and so to ensure that the

system control mechanism runs without interruption

**hot-replaceable** A *module* that can be replaced without stopping the system.

I<sup>2</sup>C Inter Integrated Circuit

IOMMU Input/Output Memory Management Unit

**LED** Light-Emitting Diode.

**location** A slot where a *module* can be inserted. Each location has a unique name and is clearly marked on the chassis.

**lockstep** The process by which two *CPUsets* work in synchronization.

**losing side** The side of a *split* system which has a new identity when rebooted.

MBD Motherboard.

Mbus Maintenance bus.

**module** An assembly that can be replaced without requiring the base machine to be returned to the factory. A module is a physical assembly that has a module number which is stored in the software on the machine, generally in the *EEPROM* of the physical assembly

**PCI** Peripheral Component Interconnect.

**PCIO** PCI-to-Ebus2/Ethernet controller *ASIC*.

**PRI** Processor re-integration. The process by which the two CPUsets come into *lockstep* to function as a fault tolerant system. *Re-integration* is preferred.

PROM Programmable Read Only Memory.

PSU Power Supply Unit.

RAS Reliability, Availability and Serviceability.

**RCP** Remote Control Processor.

RMM Removable Media Module.

**RS232** An EIA specification that defines the interface between DTE and DCE using asynchronous binary data interchange.

**SC\_UP**+ System controller *ASIC*.

**side** One *CPUset* and its associated *modules*, capable of running as a standalone system. A side is one half of a *fault tolerant* system or one of two systems in a *split* system.

**SPF** Single Point of Failure.

**split system** A system whose two *sides* run as separate systems.

**stealthy PRI** Stealthy processor re-integration. Processor re-integration (*PRI*) which is completed without user intervention.

**subsystem** (*CMS*) A fault tolerant configuration of *modules* defined in the CMS.

**system attribute** (*CMS*) An attribute of a CMS object that is written only by the CMS.

**TLB** Translation Lookaside Buffer. The hardware which handles the mapping of virtual addresses to real addresses.

The side of a split system which retains the identity of the previous fault tolerant system. surviving side

> UPA-to-PCI bridge (U2P) ASIC. U2P

**UPA** UltraSPARC Port Architecture.

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